ABSTRACT

METHOD FOR AFFIXING ADHESIVE TAPE FOR DIE BONDING AND METHOD OF MOUNTNG ELECTRONIC COMPONENT

First, a prescribed position (2) on a substrate (1) is recognized by an image pickup mechanism (14). Then, a piece (12) including an adhesive film (10) is held by a holding mechanism (13). Thereafter, the holding mechanism (13) is moved to affix the adhesive film (10) to the prescribed position (2) based on a result of recognition of the prescribed position (2). In the above-described step, the holding mechanism (13) and the image pickup mechanism (14) can move independently of each other. Therefore, the step of recognizing the prescribed position (2) and the step of holding the piece (12) can be performed concurrently.

FIG. 3